



Statements of Support for UCle 1.1 Specification

Alibaba

"It's thrilling to witness the introduction of new features, like automotive enhancement and full-stack streaming protocol, in UCle 1.1. These enhancements are expected to further broaden the applications of UCle and fuel the rapid growth of the chiplet ecosystem. Alibaba Cloud is proud to be part of this journey."

Dr. Jian Chen, Chief Architect of Cloud Server Infrastructure, Alibaba Cloud

AMD

"The UCle 1.1 specification, which adds new features to optimize silicon and packaging costs, additional protocol flexibility and automotive use cases, takes the first step towards establishing a chiplet ecosystem. We are proud of the UCle Consortium's progress so far and look forward to establishing a truly pervasive universal chiplet ecosystem."

Nathan Kalyanasundharam, Corporate Fellow and AMD Infinity Fabric Lead Architect, AMD

Arm

"As compute requirements continue to grow and evolve across all industries, we must deliver scalable, cost-effective solutions and new approaches. Arm partners are already delivering chiplet-based solutions in infrastructure applications; in automotive, chiplets can reduce time to market, allow for new performance points and enable unique SoC designs in applications such as ADAS and infotainment, while still delivering the dedicated features tailored to the safety and real-time needs of the market. Arm will continue to work with industry leaders in the UCle Consortium on standards and specifications like the UCle 1.1 Specification as the Consortium expand to increase interoperability and address industry needs."

Andy Rose, VP Technology Strategy and Fellow, Arm

Astera Labs

"Chiplets will play a significant role in enabling accelerated computing for AI infrastructure and requires a robust interoperable chiplet ecosystem. The UCle 1.1 Specification is a big step on the road to interoperability, providing critical enhancements to support more usage models and compliance testing. Astera Labs' is proud to support this broad industry effort and work with our partners and customers to expand our roadmap of connectivity solutions."

Jitendra Mohan, CEO, Astera Labs

Blue Cheetah Analog Design

"UCle has gained industry-wide attention and highlighted the tremendous interest in an open chiplet economy. The UCle 1.1 Specification includes many important clarifications and improvements, bringing the industry closer to this goal. As the chiplet landscape progresses, Blue Cheetah will continue to enable customers to adopt the chiplet paradigm through its customized die-to-die interface solutions, including support for UCle."

Elad Alon, CEO, Blue Cheetah Analog Design



Cadence

“Cadence is excited to be contributing superior and easy-to-integrate UCle IP solutions to the standardized chiplet ecosystem. As a contributor to the UCle Consortium and its working groups, Cadence is well positioned to implement new ECNs from the UCle 1.1 Specification to enable rapid adoption and meet demands for emerging market segments including automotive. The pre-verified full solution package allows our customers to quickly and seamlessly integrate Cadence’s UCle IP, reducing product development time. Multiple Tier-1 customers and automotive customers have already adopted Cadence’s UCle solutions for their new designs.”

Boyd Phelps, Senior Vice President and General Manager, IP Group, Cadence

Eliyan

“Eliyan is proud to be contributing and sharing our expertise in high-speed and power-efficient interconnect to the further evolution of the UCle standard. The Consortium has put together an effective framework that will advance us further toward the goal of an open chiplet ecosystem and Version 1.1 of the spec includes many critical features. As a provider of a fully UCle compatible solution that has the flexibility to achieve even higher speeds and lower power, Eliyan looks forward to supporting and contributing to this die-to-die protocol.”

Patrick Soheili, Co-founder, Director and Vice President of Strategy and Business at Eliyan

Hyundai

“I am delighted to extend my enthusiastic endorsement for the UCle specification 1.1 release. The formation of the Automotive Working Group and the incorporation of automotive-specific requirements UCle 1.1's ECNs showcase the industry's commitment to advancing chiplet technology for automotive applications, promising enhanced performance and adaptability in multi-die systems for our vehicles. I look forward to the continued collaboration with UCle in driving innovation and efficiency in the automotive semiconductor ecosystem.”

Jongsun Kim, VP, Semiconductor Development Group, IATD, Hyundai Motor Group

Imec

“With the release of UCle™ Specification 1.1, new Engineering Change Notices (ECNs), and the formation of the UCle Consortium Automotive Working Group, we excitedly anticipate the rapid adoption of chiplets within the automotive industry.””

Bart Plackle, VP Automotive, Imec

Intel

“Intel is proud to be a founding member of the UCle consortium. Chiplets are continuing to become a critical technology for the semiconductor industry. Intel Foundry Services (IFS) is focusing on UCle to enable our foundry customers to build interoperable silicon solutions, based upon industry standards.”

Bob Brennan, Vice President of Customer Enablement, Intel Foundry Services



Marvell

"Marvell believes that standardization of die-to-die interfaces will enable significant innovation and scaling of cloud-optimized silicon. We are very supportive of the latest UCle 1.1 Specification release as it provides sufficient flexibility to enable a range of applications in the growing market for chiplet-based semiconductor designs."

Mark Kuemerle, VP Technology Compute & Custom Solutions, Marvell

Mercedes

"As the first Automotive OEM member of UCle™, Mercedes-Benz is committed to standardizing chiplet technologies. We appreciate the UCle consortium for providing a platform to present automotive-semiconductor requirements, resulting in the unanimous acceptance of the UCle specification V1.1. We are dedicated to revolutionizing the automotive computing landscape with the goal of increasing road safety and giving customers back time spent on the road."

Markus Schäfer, Member of the Board of Management of Mercedes-Benz Group AG, Chief Technology Officer

proteanTecs

"The UCle 1.1 specification is a pivotal milestone toward building an open chiplet ecosystem and is a testament to the invaluable work done by UCle Consortium members. proteanTecs is pleased to see new lane monitoring capabilities included, which will improve the visibility of the link's performance and health. Interconnect monitoring is crucial for the adoption of the UCle standard in mission-critical applications, such as automotive, and will make compliance testing more accurate and transparent."

Nir Sever, Sr. Director of Business Development, proteansTecs

Socionext Inc.

"Socionext strives to provide optimum silicon solutions to customers who seek innovations in the global marketplace. As Moore's law slows down, the industry is facing new challenges that include enhancing data traffic in high-performance computing, balancing requirements for computing performance and footprint, as well as heterogeneous integration of high-speed I/O and high-speed computing devices. The UCle standard plays a key role in addressing these challenges. In particular, the UCle 1.1 Specification has enhanced features for functional safety, and we expect its adoption will be accelerated in the automotive domain, one of our primary focus areas."

Hisato Yoshida, Corporate Executive Vice President and Head of Global Business Development, Socionext

Samsung

"As Moore's Law slows down, the semiconductor industry is facing many new challenges and limitations. The Samsung AVP Team is excited to tackle heterogeneous integration and advanced packaging, which will help overcome the limitations of Moore's law-like scaling. Heterogeneous integration will play an important role in innovations to meet the ever-increasing computing performance requirements. We are excited to be part of the successful distribution of the UCle 1.1 Specification and as one of the co-founders of the UCle Consortium, Samsung will continue our contribution toward developing the 3DIC, memory interconnect, automotive chiplet, and further standard enhancements."

Dr. Moonsoo Kang, Executive Vice President and Head of the Advanced Packaging Business Team, Samsung Electronics



Synopsys

“As multi-die systems revolutionize the semiconductor industry in architectural form and function, the UCle 1.1 specification enables rapid adoption by providing reliable interoperability between heterogeneous dies on different process nodes. As an active member of the UCle Consortium, Synopsys helps designers get a jump start on their multi-die system designs with our complete UCle IP and verification IP solutions, which have been adopted by multiple customers.”

John Koeter, Senior Vice President of Marketing and Strategy for IP, Synopsys